ABSTRACT OF THE DISCLOSURE

An image sensor includes lower and upper metal sheet sets, an encapsulant, a photosensitive chip, wires, and a transparent layer. The lower metal sheet set includes plural lower metal sheets and a middle board among and flush with the lower metal sheets. The upper metal sheet set includes plural upper metal sheets stacked on the lower metal sheets, respectively. The encapsulant encapsulates the upper and lower metal sheets and the middle board with upper surfaces of the upper sheets, lower surfaces of the lower sheets, and upper and lower surfaces of the middle board exposed from the encapsulant, and with a frame layer formed around the upper sheets to define a chamber. The chip is mounted to the middle board and located within the chamber. The wires electrically connect the chip to the upper metal sheets. The transparent layer is arranged on the frame layer to cover the chip.

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